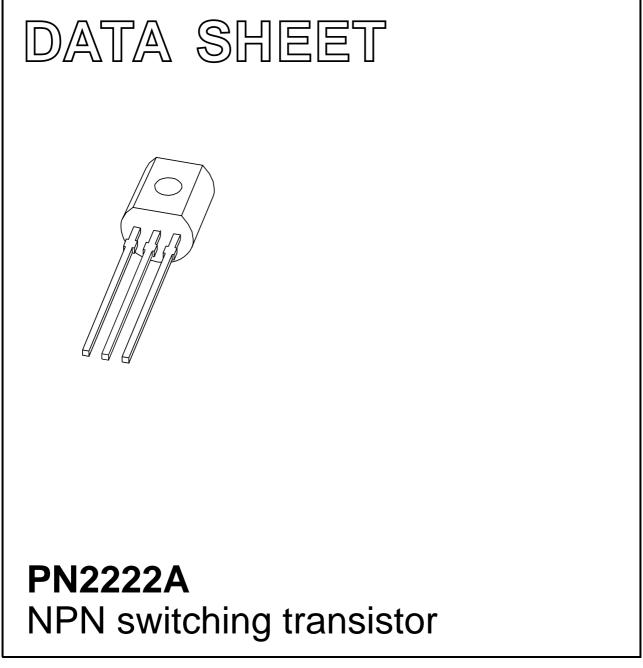
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 May 21 2004 Oct 11



FEATURES

- High current (max. 600 mA)
- Low voltage (max. 40 V).

APPLICATIONS

• General purpose switching and linear amplification.

DESCRIPTION

NPN switching transistor in a TO-92; SOT54 plastic package. PNP complement: PN2907A.

PINNING

PIN	DESCRIPTION	
1	collector	
2	base	
3	emitter	

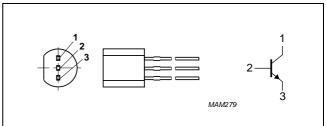


Fig.1 Simplified outline (TO-92; SOT54) and symbol.

ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
ITFE NOWBER	NAME	NAME DESCRIPTION			
PN2222A	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54		

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	75	V
V _{CEO}	collector-emitter voltage	open base	-	40	V
V _{EBO}	emitter-base voltage	open collector	-	6	V
I _C	collector current (DC)		-	600	mA
I _{CM}	peak collector current		-	800	mA
I _{BM}	peak base current		-	200	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$	-	500	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C

PN2222A

PN2222A

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	250	K/W

Note

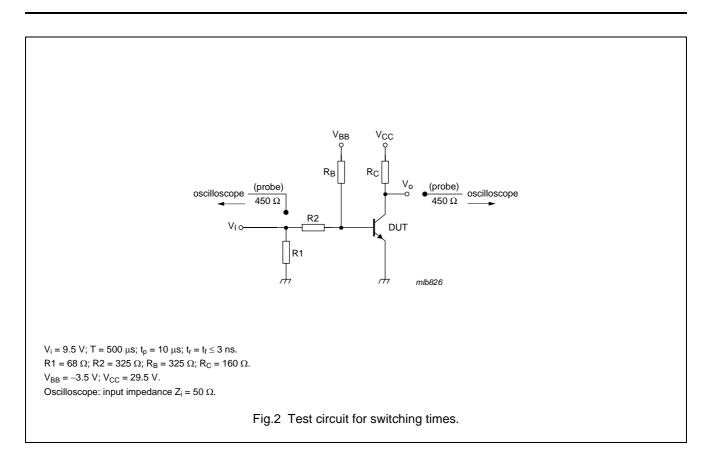
1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

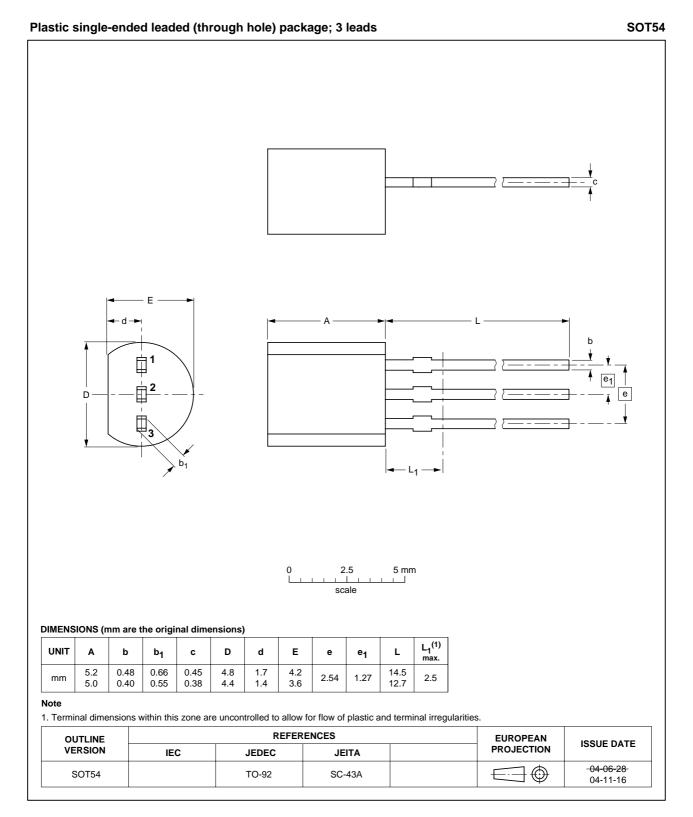
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = 60 \text{ V}; \text{ I}_{E} = 0 \text{ A}$	-	10	nA
		V _{CB} = 60 V; I _E = 0 A; T _j = 125 °C	-	10	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 3 \text{ V}; \text{ I}_{C} = 0 \text{ A}$	-	10	nA
h _{FE}	DC current gain	V _{CE} = 10 V; I _C = 0.1 mA	35	_	
		$V_{CE} = 10 \text{ V}; \text{ I}_{C} = 1 \text{ mA}$	50	-	
		$V_{CE} = 10 \text{ V}; I_{C} = 10 \text{ mA}$	75	-	
		V_{CE} = 10 V; I _C = 10 mA; T _j = -55 °C	35	-	
		V _{CE} = 1 V; I _C = 150 mA	50	-	
		V _{CE} = 10 V; I _C = 150 mA	100	300	
		V _{CE} = 10 V; I _C = 500 mA	40	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 150 mA; I _B = 15 mA	-	300	mV
		$I_{\rm C} = 500 \text{ mA}; I_{\rm B} = 50 \text{ mA}$	1	-	V
V _{BEsat}	base-emitter saturation voltage	I _C = 150 mA; I _B = 15 mA	0.6	1.2	V
		I _C = 500 mA; I _B = 50 mA	-	2	V
Cc	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0 \text{ A}; f = 1 \text{ MHz}$	-	8	pF
C _e	emitter capacitance	$V_{EB} = 500 \text{ mV}; I_{C} = i_{c} = 0 \text{ A}; f = 1 \text{ MHz}$	-	25	pF
f _T	transition frequency	V _{CE} = 20 V; I _C = 20 mA; f = 100 MHz	300	-	MHz
F	noise figure	V_{CE} = 5 V; I _C = 100 µA; R _S = 1 kΩ; f = 1 kHz	-	4	dB
Switching t	imes (between 10 % and 90 % level	is); see Fig.2	·		•
t _{on}	turn-on time	I _{Con} = 150 mA; I _{Bon} = 15 mA;	-	35	ns
t _d	delay time	I _{Boff} = −15 mA; T _{amb} = 25 °C	-	15	ns
t _r	rise time		-	20	ns
t _{off}	turn-off time		-	250	ns
ts	storage time	1	_	200	ns
t _f	fall time	1	_	60	ns

PN2222A



PACKAGE OUTLINE



PN2222A

PN2222A

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

DATA SHEET STATUS

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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